

# PSMN165-200K-VB Datasheet N-Channel 200 V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)				
200	0.260 at V <sub>GS</sub> = 10 V	3				

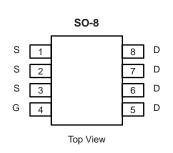
### **FEATURES**

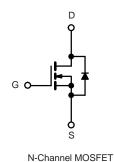
- TrenchFET<sup>®</sup> Power MOSFET
- 175 °C Junction Temperature
- PWM Optimized
- 100 % R<sub>a</sub> Tested
- Compliant to RoHS Directive 2002/95/EC



### **APPLICATIONS**

· Primary Side Switch





ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25 °C, unless otherwise noted)						
Parameter	Symbol	Limit	Unit			
Drain-Source Voltage	V <sub>DS</sub>	200	V			
Gate-Source Voltage	V <sub>GS</sub>	± 20				
Continuous Drain Current (T <sub>.J</sub> = 175 °C) <sup>b</sup>	$T_C = 25 ^{\circ}\text{C}$ $T_C = 125 ^{\circ}\text{C}$	I <sub>D</sub>	3			
Continuous Drain Current (1) = 175 C)	T <sub>C</sub> = 125 °C	טי	2.7			
Pulsed Drain Current	I <sub>DM</sub>	10	A			
Continuous Source Current (Diode Conduction)	I <sub>S</sub>	6				
Avalanche Current	I <sub>AS</sub>	6				
Single Pulse Avalanche Energy	L = 0.1 mH	E <sub>AS</sub>	18	mJ		
Maximum Power Dissination	T <sub>C</sub> = 25 °C	PD	96 <sup>b</sup>	W		
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	' D	3 <sup>a</sup>			
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C			

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
hunding to Ambigut	t ≤ 10 s	- R <sub>thJA</sub>	15	18	°C/W	
Junction-to-Ambient <sup>a</sup>	Steady State		40	50		
Junction-to-Case (Drain)		R <sub>thJC</sub>	0.85	1.1		

#### Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. See SOA curve for voltage derating.

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Parameter	Symbol	Test Conditions	Min.	Typ. <sup>a</sup>	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	200			V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2		4		
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V <sub>DS</sub> = 200 V, V <sub>GS</sub> = 0 V			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 200 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50	μΑ	
		V <sub>DS</sub> = 200 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			250		
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = 5 V, V <sub>GS</sub> = 10 V	40			Α	
		$V_{GS} = 10 \text{ V}, I_D = 3 \text{ A}$		0.260			
- 1 - 1 - 1 - h	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3 A, T <sub>J</sub> = 125 °C		0.310			
Drain-Source On-State Resistance <sup>b</sup>		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3 A, T <sub>J</sub> = 175 °C		0.330		Ω	
		V <sub>GS</sub> = 6 V, I <sub>D</sub> = 3 A		0.292		1	
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 3 A		35		S	
Dynamic <sup>a</sup>							
Input Capacitance	C <sub>iss</sub>			1800		pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, F = 1 \text{ MHz}$		180			
Reverse Transfer Capacitance	C <sub>rss</sub>			80			
Total Gate Charge <sup>c</sup>	$Q_g$			34	51		
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = 100 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 3 \text{ A}$		8		nC	
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$			12			
Gate Resistance	R <sub>g</sub>		0.5		2.9	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			15	25		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 100 \text{ V}, R_{L} = 5.2 \Omega$		50	75		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 3 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		30	45	- ns -	
Fall Time <sup>c</sup>	t <sub>f</sub>			60	90		
Source-Drain Diode Ratings and Char	acteristics (7	<sub>C</sub> = 25 °C)					
Pulsed Current	I <sub>SM</sub>				5	Α	
Diode Forward Voltage <sup>b</sup>	$V_{SD}$	I <sub>F</sub> = 3 A, V <sub>GS</sub> = 0 V		0.9	1.5	V	
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 3 A, dI/dt = 100 A/µs		180	250	ns	

#### Notes:

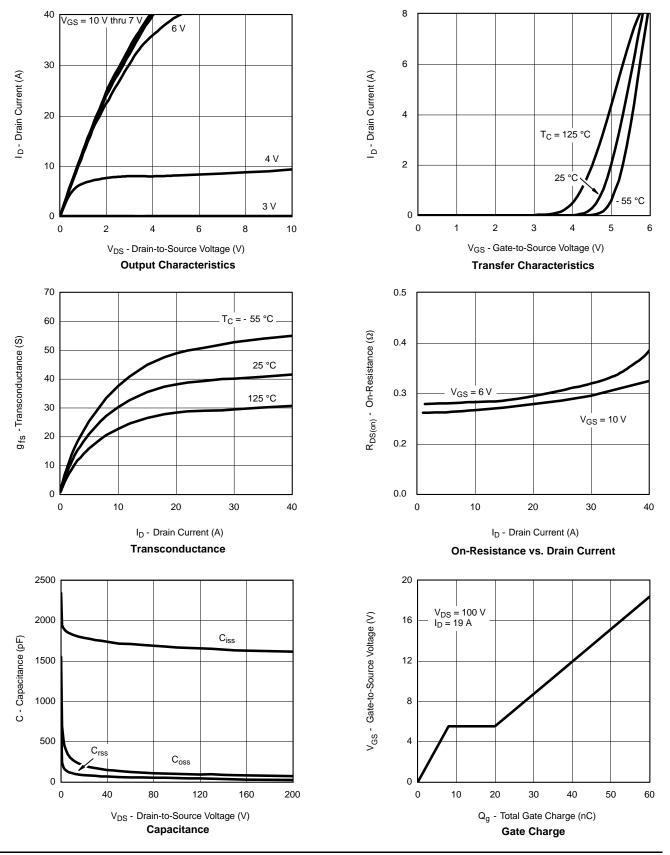
- a. Guaranteed by design, not subject to production testing.
- b. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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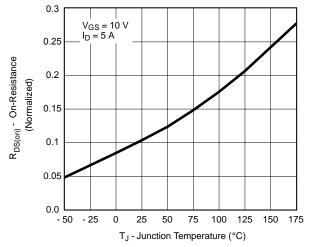
### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



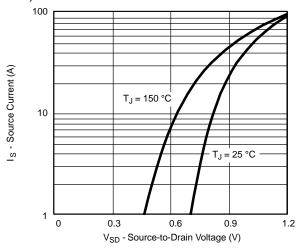
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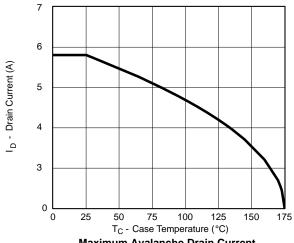


On-Resistance vs. Junction Temperature

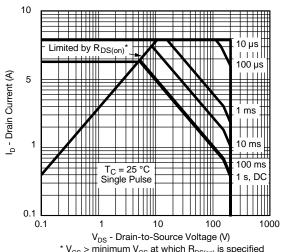


Source-Drain Diode Forward Voltage

#### THERMAL RATINGS

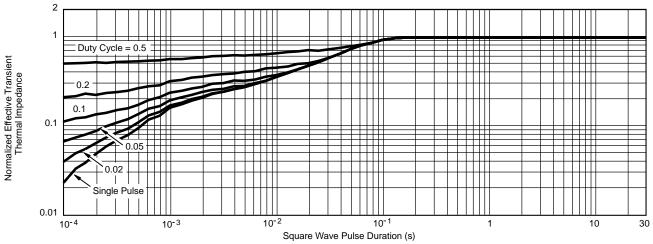


Maximum Avalanche Drain Current vs. Case Temperature



\* V<sub>GS</sub> > minimum V<sub>GS</sub> at which R<sub>DS(on)</sub> is specified

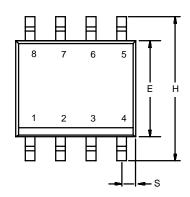
Safe Operating Area

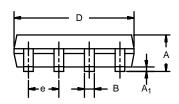


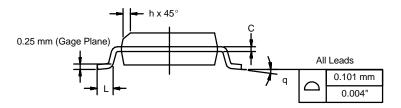
Normalized Thermal Transient Impedance, Junction-to-Case



**SOIC (NARROW): 8-LEAD**JEDEC Part Number: MS-012







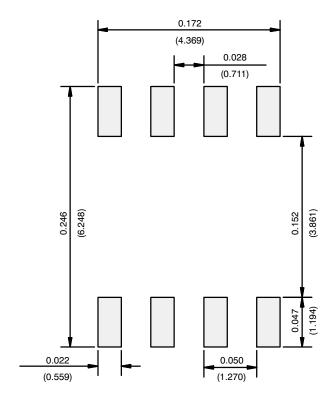
	MILLIM	IETERS	INC	HES		
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A <sub>1</sub>	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
E	3.80	4.00	0.150	0.157		
е	1.27 BSC		0.050 BSC			
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
FCN: C-06527-Rev I 11-Sen-06						

ECN: C-06527-Rev. I, 11-Sep-06

DWG: 5498



## **RECOMMENDED MINIMUM PADS FOR SO-8**



Recommended Minimum Pads Dimensions in Inches/(mm)



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